

## **IRF7313TRPBF Datasheet**

# **Dual N-Channel 30-V (D-S) MOSFET**

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)		
30	$0.022 \text{ at V}_{GS} = 10 \text{ V}$	6.8	15 nC		
30	0.026 at V <sub>GS</sub> = 4.5 V	6.0	10110		

 $D_1$ 

 $D_2$ 

SO-8

Top View

#### **FEATURES**

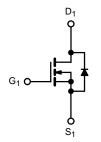
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % UIS Tested
- 100 % R<sub>q</sub> Tested
- Compliant to RoHS Directive 2002/95/EC

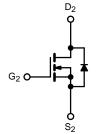


COMPLIANT HALOGEN FREE

#### **APPLICATIONS**

- Set Top Box
- Low Current DC/DC





N-Channel MOSFET

N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATIN</b>	IGS $T_A = 25  ^{\circ}C$	unless otherw	vise noted	
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	30	V
Gate-Source Voltage		$V_{GS}$	± 20	V
	T <sub>C</sub> = 25 °C		6.8 <sup>a</sup>	
Continuous Drain Current (T <sub>.1</sub> = 150 °C)	$T_{\rm Current} (T = 150  {\rm °C})$	1 ,	5.6	
Continuous Brain Current (1) = 100 °C)	T <sub>A</sub> = 25 °C	l <sub>D</sub>	6.2 <sup>b, c</sup>	
	T <sub>A</sub> = 70 °C		5.2 <sup>b, c</sup>	Α
Pulsed Drain Current		I <sub>DM</sub>	30	^
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	1_	2.25	
	T <sub>A</sub> = 25 °C	'S	1.48 <sup>b, c</sup>	
Single Pulse Avalanche Current		I <sub>AS</sub>	5	
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	1.25	mJ
	T <sub>C</sub> = 25 °C		2.7	
Maximum Dawar Dissination	T <sub>C</sub> = 70 °C	D.	1.77	w
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	1.78 <sup>b, c</sup>	VV
	T <sub>A</sub> = 70 °C		1.14 <sup>b, c</sup>	
Operating Junction and Storage Temperatur	$T_{\rm J}, T_{\rm sto}$	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>a, c, d</sup>	t ≤ 10 s	R <sub>thJA</sub>	58	70	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	$R_{th,IF}$	38	45	] 5/ ۷۷		

#### Notes:

- a. Package limited, T<sub>C</sub> = 25 °C.
  b. Surface Mounted on 1" x 1" FR4 board.
- d. Maximum under Steady State conditions is 110 °C/W.



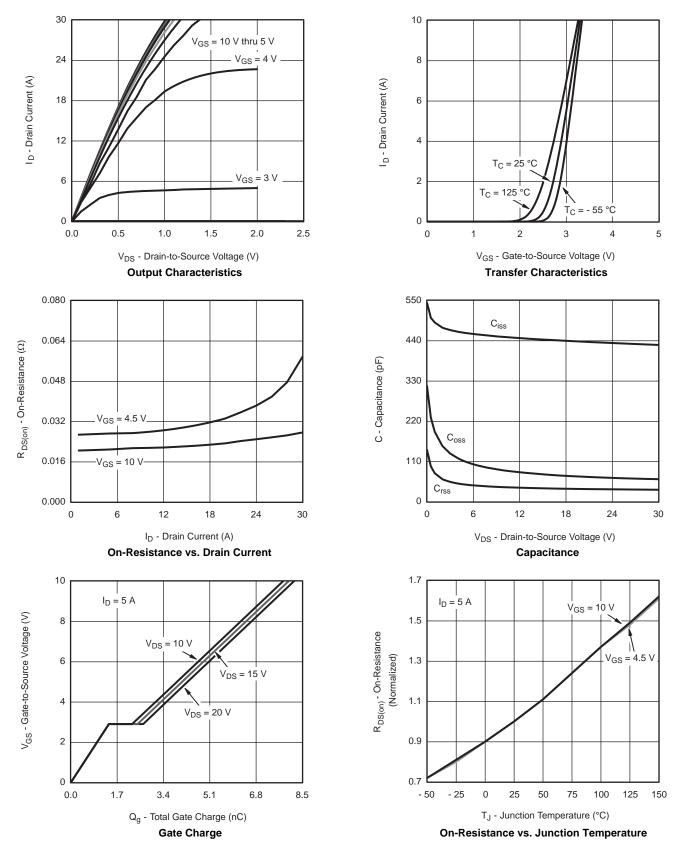
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static			•			•
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30			V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = 250 μA		32		mV/°C
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA		- 5.0		
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_{D} = 250 \mu A$	1.0		2.5	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zara Oata Valta va Daria Oamani	I <sub>DSS</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1	
Zero Gate Voltage Drain Current		V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			10	μA
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	10			Α
	5	$V_{GS} = 10 \text{ V, } I_D = 5 \text{ A}$	0.022			
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 4 \text{ A}$		0.026		Ω
Forward Transconductance <sup>a</sup>	g <sub>fs</sub>	$V_{DS} = 10 \text{ V}, I_D = 5 \text{ A}$		16		S
Dynamic <sup>b</sup>	<u> </u>		1		l	l
Input Capacitance	C <sub>iss</sub>			586		pF
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		117		
Reverse Transfer Capacitance	C <sub>rss</sub>			55		
Total Cata Chausa	Q <sub>g</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 5 \text{ A}$		15		nC
Total Gate Charge				3.7	5.6	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 5 \text{ A}$		1.4		
Gate-Drain Charge	$Q_{gd}$			1.05		
Gate Resistance	$R_g$	f = 1 MHz	0.8	4.3	8.6	Ω
Turn-On Delay Time	t <sub>d(on)</sub>			12	24	
Rise Time	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_L$ = 3 $\Omega$		55	100	-
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D\cong 5$ A, $V_{GEN}$ = 4.5 V, $R_g$ = 1 $\Omega$		11	22	
Fall Time	t <sub>f</sub>			8	16	
Turn-On Delay Time	t <sub>d(on)</sub>			4	8	ns
Rise Time	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_L$ = 3 $\Omega$		9	18	- - -
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D\cong 5$ A, $V_{GEN}$ = 10 V, $R_g$ = 1 $\Omega$		10	20	
Fall Time	t <sub>f</sub>			6	12	
<b>Drain-Source Body Diode Characteristic</b>	s					_
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			2.25	۸
Pulse Diode Forward Current	I <sub>SM</sub>				24	- A
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = 2 A, V <sub>GS</sub> = 0 V		0.8	1.2	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>			11	20	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	L _ E A dl/dt _ 100 A/::2 T _ 25 °C		4	8	nC
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = 5 \text{ A}, \text{ dI/dt} = 100 \text{ A/µs}, T_J = 25 °C$		7		
Reverse Recovery Rise Time t <sub>b</sub>				4		ns

#### Notes:

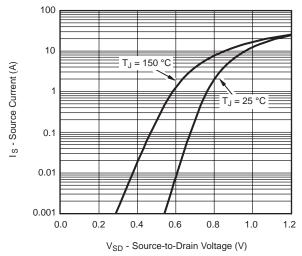
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

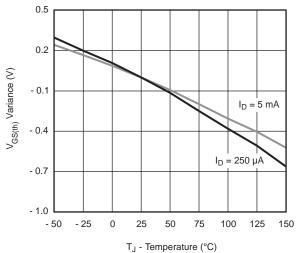




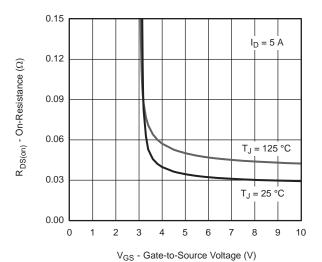




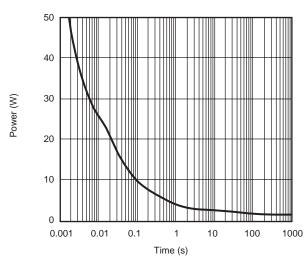
#### Source-Drain Diode Forward Voltage



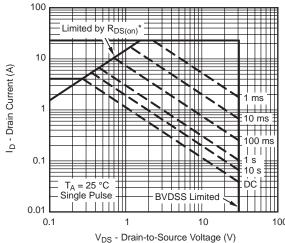
**Threshold Voltage** 



On-Resistance vs. Gate-to-Source Voltage



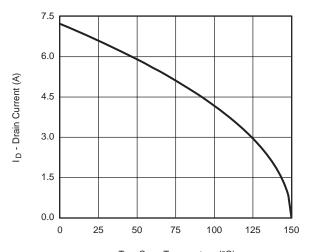
Single Pulse Power



\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

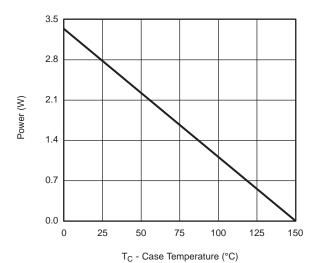
Safe Operating Area, Junction-to-Ambient

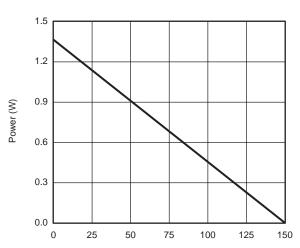




T<sub>C</sub> - Case Temperature (°C)

### **Current Derating\***





T<sub>A</sub> - Ambient Temperature (°C)

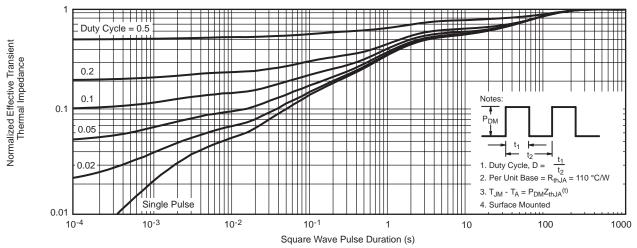
服务热线:400-655-8788 5

Power, Junction-to-Foot

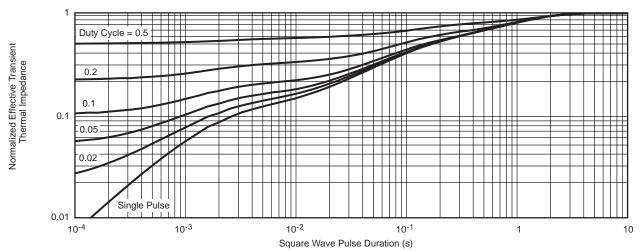
Power, Junction-to-Ambient

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





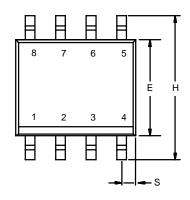
Normalized Thermal Transient Impedance, Junction-to-Ambient

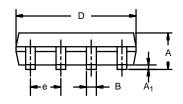


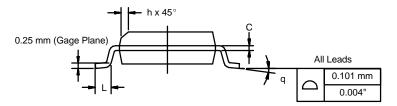
Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







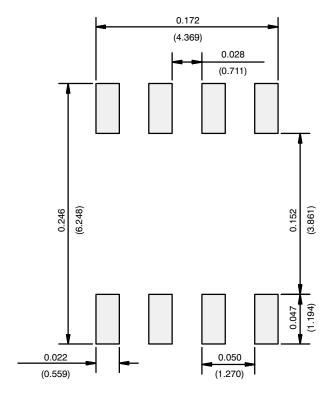
	MILLIM	IETERS	INC	HES	
DIM	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A <sub>1</sub>	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27 BSC		0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
FCN: C-06527-Rev I 11-Sen-06					

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498



### **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)



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